

HRW0202A

Silicon Schottky Barrier Diode for Rectifying

REJ03G0152-0600Z

(Previous: ADE-208-209E)

Rev.6.00

Dec.15.2003

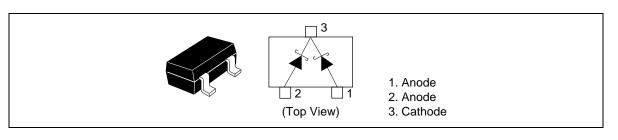
Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- MPAK Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code	
HRW0202A	S17	MPAK	

Pin Arrangement



Absolute Maximum Ratings *1

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Repetitive peak reverse voltage	V _{RMM} * ¹	20	V	
Average rectified current	l ₀ * ²	200	mA	
Non-Repetitive peak forward surge current	I _{FSM} * ³	3	А	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

Notes: 1. Two device total

2. See from Fig.4 to Fig.7

3. 10ms sine wave 1 pulse

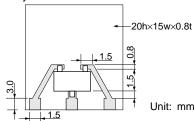
Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

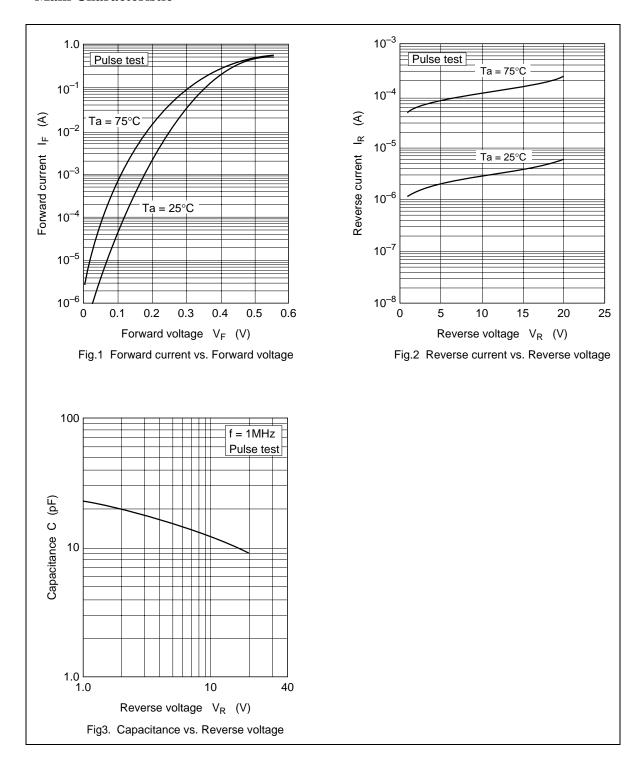
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _F	_	_	0.40	V	I _F = 100 mA
Reverse current	I _R	_	_	50	μΑ	V _R = 20 V
Thermal resistance	R _{th(j-a)}	_	350	_	°C/W	Polyimide board *2

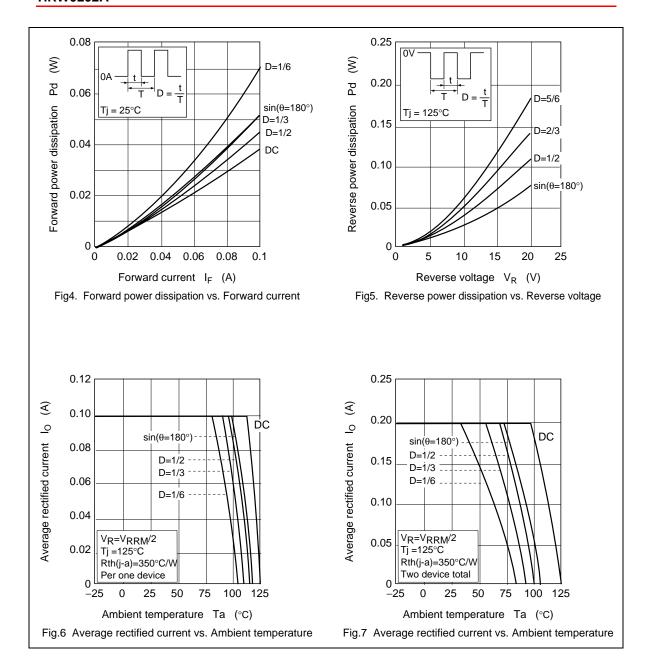
Notes: 1. Per one device

2. Polyimide board

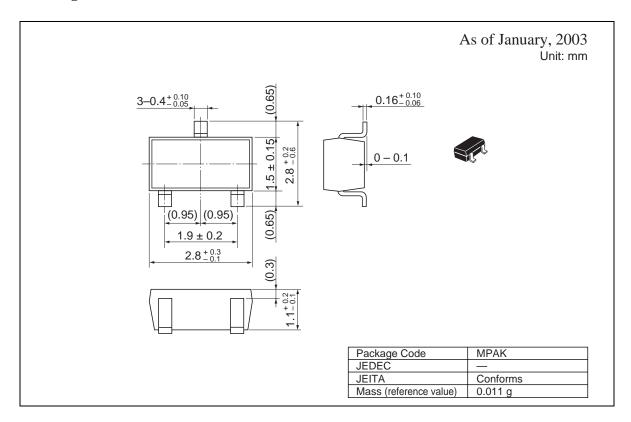


Main Characteristic





Package Dimensions



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